

## 複合光學量測系統 Hybrid Optical Metrology

### 產品特色 Product Feature

- 共光路微型模組設計, Compact Optical Module Design

### 產品規格 Specifications

- Wafer Size: 4", 6", 8", 12" (glass carrier compatible)
- Objective Lens: 5X, 20X, 50X, 100X (or other option)

#### 3D Profile Measurement:

- Scan Range: up to 400  $\mu\text{m}$  (or other option)
- Step Height Accuracy: < 0.75 %
- Step Height Repeatability( $\sigma$ ): < 0.1 %

#### Thin Film Thickness Measurement:

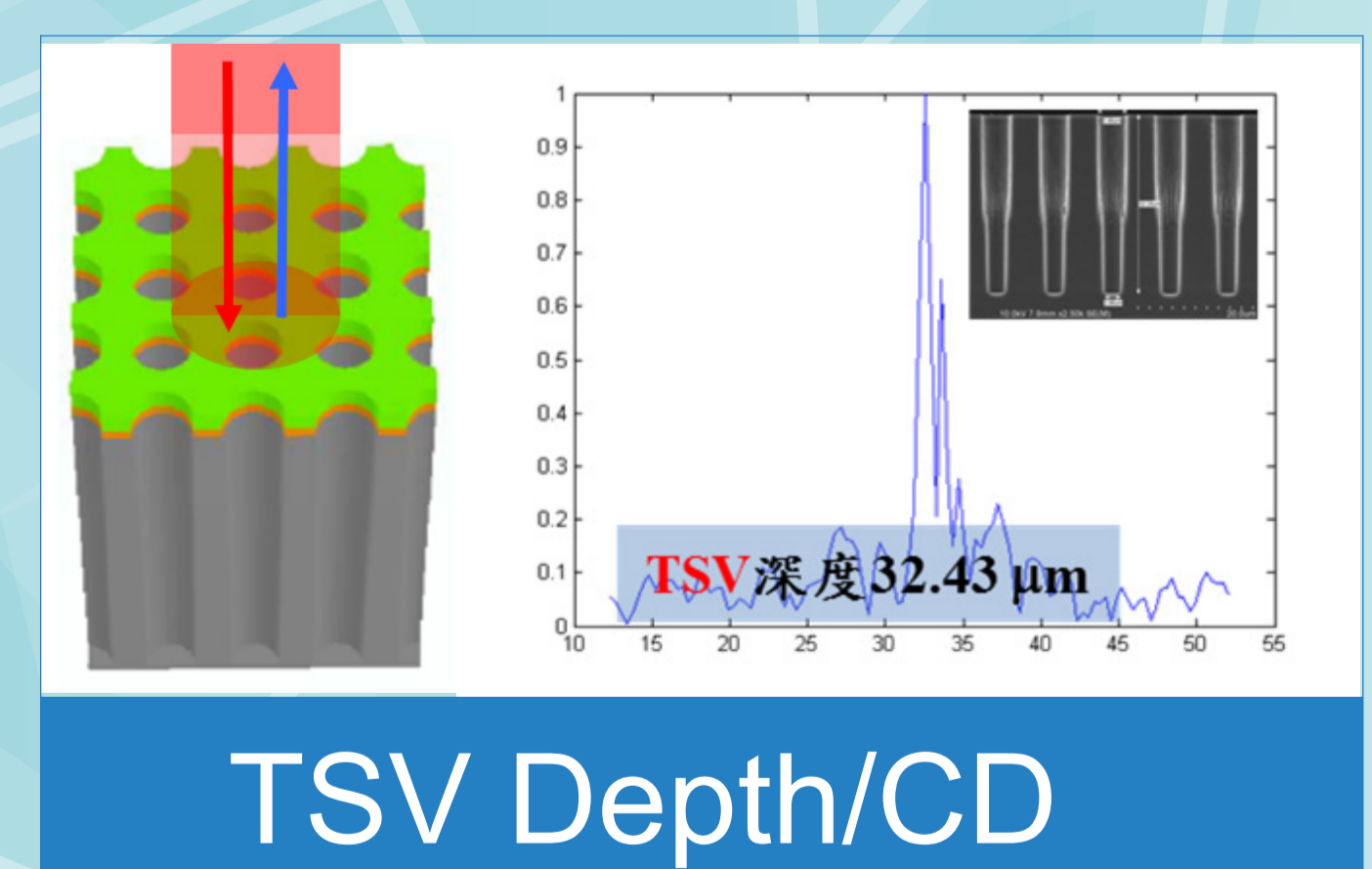
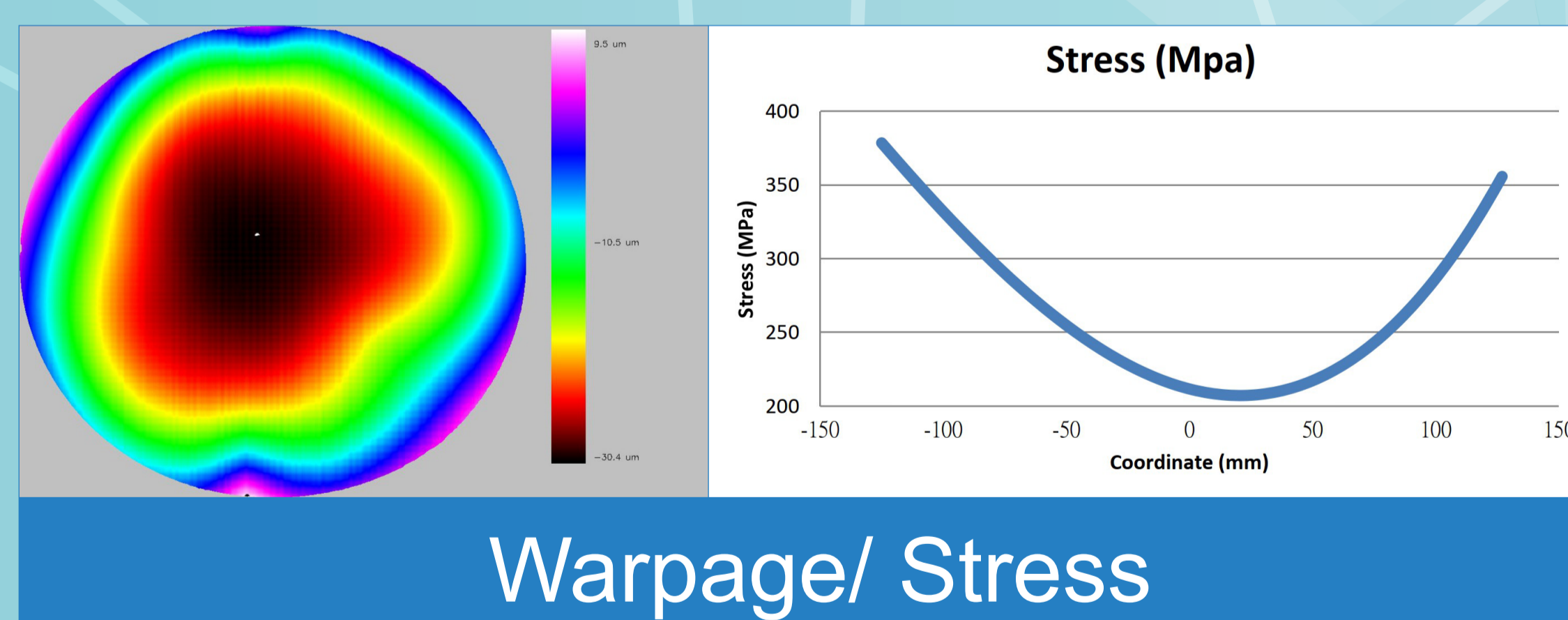
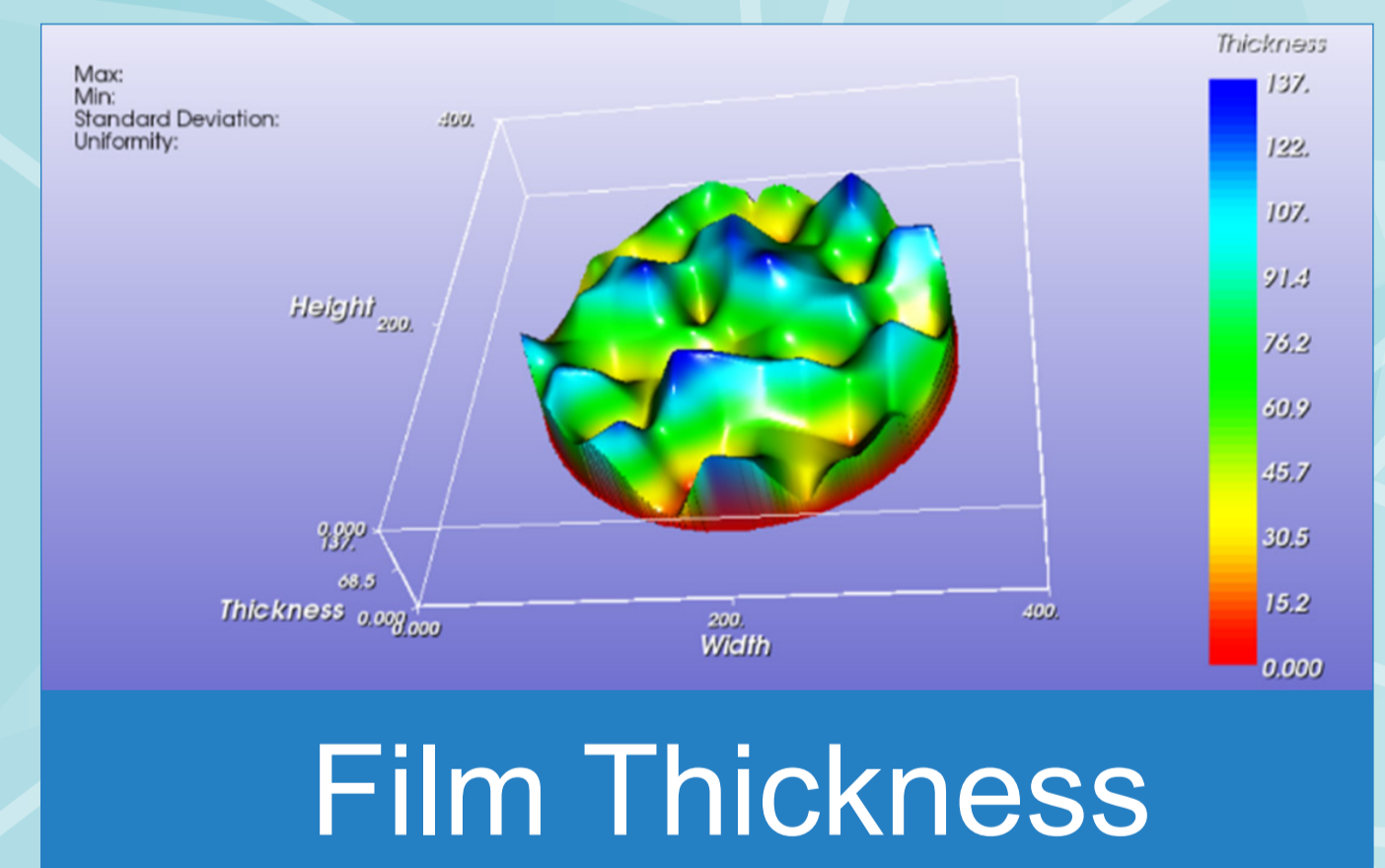
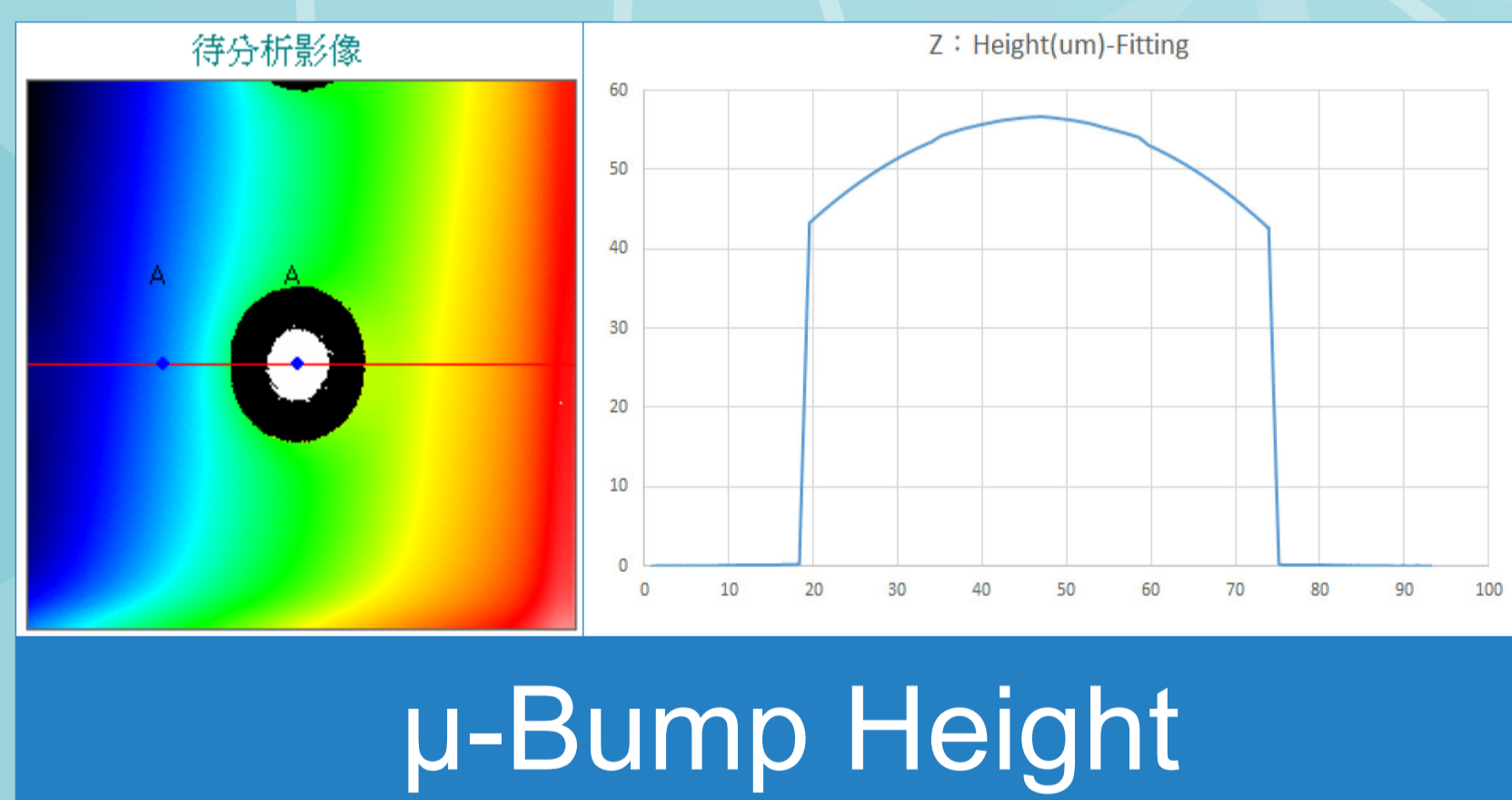
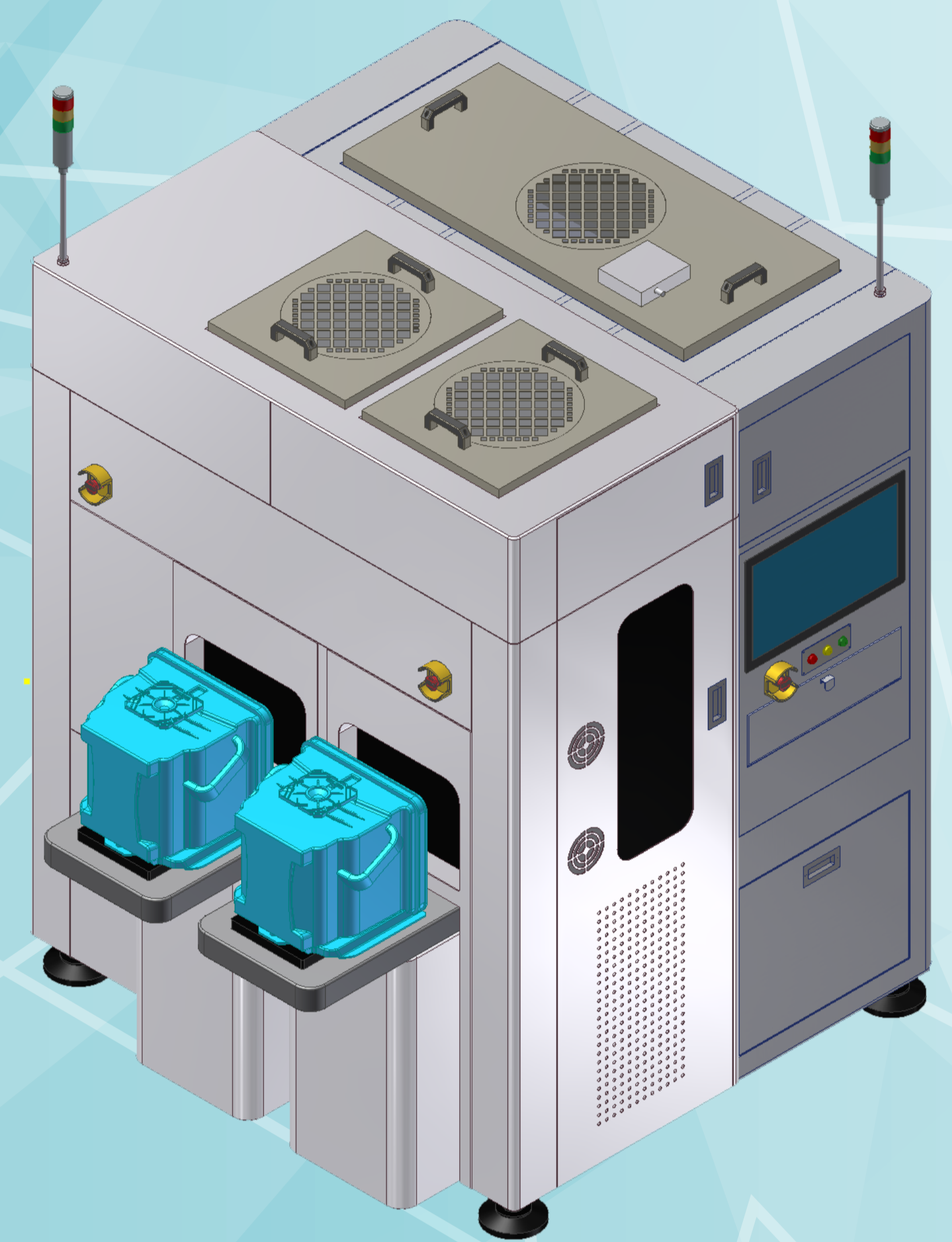
- Thickness Range: 500  $\text{\AA}$  ~ 30  $\mu\text{m}$  (option to 800  $\mu\text{m}$ )
- Thickness Repeatability: < 10  $\text{\AA}$  @ 5000  $\text{\AA}$  Oxide on Si substrate

#### Film Stress Measurement:

- Stress Repeatability : < 0.1 MPa

#### TSV Measurement:

- Aspect Ratio:  $\leq 20$
- Depth Repeatability:  $\leq 0.2 \mu\text{m}$
- CD Repeatability :  $\leq 0.5 \mu\text{m}$



### 應用範圍 Applications

- 關鍵尺寸量測,  $\mu\text{-Bump/RDL}$  Measurement
- 薄膜厚度量測, Thin Film/Wafer Thickness Measurement
- 薄膜應力量測, Thin Film Stress Measurement
- 矽通孔深量測, High Aspect Ratio TSV Depth/CD Measurement